

## DECLARATION FOR PATENT APPLICATION (WITH POWER OF ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD OF FABRICATING CHIP-SCALE PACKAGES AND RESULTING STRUCTURES, the specification of which (check one):

☒ is attached hereto.

☐ was filed on \_\_\_\_\_ as United States application serial no. \_\_\_\_\_ and was amended on \_\_\_\_\_.

☐ was filed on \_\_\_\_\_ as PCT international application no. \_\_\_\_\_ and was amended under PCT Article 19 on \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to the patentability of the subject matter claimed in this application, as "materiality" is defined in Title 37, Code of Federal Regulations § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate or § 365(a) of any PCT international application(s) designating at least one country other than the United States of America listed below and on any attached continuation page and have also identified below and on any attached continuation page any foreign application for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America having a filing date before that of the application(s) on which priority is claimed.

Prior foreign/PCT application(s):

(number)	(country)	(day/month/year filed)	Priority Claimed	
			Yes	No
_____	_____	_____	_____	_____
_____	_____	_____	_____	_____

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or § 365(c) of PCT international application(s) designating the United States of America listed below and on any attached continuation page and, insofar as the subject matter of each of the claims of this application is not disclosed in any such prior application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of such prior application and the national or PCT international filing date of this application:

_____ (application serial no.)	_____ (filing date)	_____ (status - pending, patented or abandoned)
_____ (application serial no.)	_____ (filing date)	_____ (status - pending, patented or abandoned)

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

_____ (provisional application no.)	_____ (filing date)
-------------------------------------	---------------------

I hereby appoint the following Registered Practitioners to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

David V. Trask, Reg. No. 22,012  
Laurence B. Bond, Reg. No. 30,549  
Allen C. Turner, Reg. No. 33,041  
Stephen R. Christian, Reg. No. 32,687  
Paul C. Oestreich, Reg. No. 44,983  
Kenneth C. Booth, Reg. No. 42,342  
Michael L. Lynch, Reg. No. 30,871

William S. Britt, Reg. No. 20,969  
Joseph A. Walkowski, Reg. No. 28,765  
Kent S. Burningham, Reg. No. 30,453  
Brick G. Power, Reg. No. 38,581  
Devin R. Jensen, Reg. No. 44,805  
Samuel E. Webb, Reg. No. 44,394  
Lia M. Pappas, Reg. No. 34,095

Thomas J. Rossa, Reg. No. 26,799  
James R. Duzan, Reg. No. 28,393  
Edgar R. Cataxinos, Reg. No. 39,931  
Kenneth B. Ludwig, Reg. No. 42,814  
Eleanor V. Goodall, Reg. No. 35,162  
David L. Stott, Reg. No. 43,937

Address all correspondence to: Joseph A. Walkowski, telephone no. (801) 532-1922.  
**TRASK, BRITT & ROSSA**  
P.O. BOX 2550  
Salt Lake City, Utah 84110

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first joint inventor: Tongbi Jiang

Inventor's signature \_\_\_\_\_ Date 11/11/00

Residence: Boise, Idaho

Citizenship: P.R. China

Post Office Address: 197 E. Mallard Drive, #225, Boise, Idaho 83706

**Inventor name(s) appearing on first declaration page: Tongbi Jiang**

Full name of second joint inventor: Edward A. Schrock

Date \_\_\_\_\_

**Citizenship:** U.S.A.

Post Office Address: 3188 E. Whitman, Boise, Idaho 83714

[illegible]

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<b>Applicant:</b>	Jiang et al.	<b>Examiner:</b>	Unknown
<b>Serial No.:</b>	Not Yet Assigned	<b>Group Art Unit:</b>	Unknown
<b>Filed:</b>		<b>Attorney Docket No.:</b>	3815US (98-0670)
<b>Title:</b>	METHOD OF FABRICATING CHIP-SCALE PACKAGES AND RESULTING STRUCTURES		

**POWER OF ATTORNEY BY ASSIGNEE**  
**AND CERTIFICATE UNDER 37 CFR § 3.73(b)**

Assistant Commissioner for Patents  
 Washington, D.C. 20231

Sir:

MICRON TECHNOLOGY, INC., assignee of the entire right, title and interest by assignment from the inventor(s) in the above-identified application, hereby appoints the following attorneys and agents:

David V. Trask, Reg. No. 22,012	William S. Britt, Reg. No. 20,969	Thomas J. Rossa, Reg. No. 26,799
Laurence B. Bond, Reg. No. 30,549	Joseph A. Walkowski, Reg. No. 28,765	James R. Duzan, Reg. No. 28,393
Allen C. Turner, Reg. No. 33,041	Kent S. Burningham, Reg. No. 30,453	Edgar R. Cataxinos, Reg. No. 39,931
Stephen R. Christian, Reg. No. 32,687	Brick G. Power, Reg. No. 38,581	Kenneth B. Ludwig, Reg. No. 42,814
Paul C. Oestreich, Reg. No. 44,983	Devin R. Jensen, Reg. No. 44,805	David L. Stott, Reg. No. 43,937
Kenneth C. Booth, Reg. No. 42,342	Samuel E. Webb, Reg. No. 44,394	Eleanor V. Goodall, Reg. No. 35,162
Michael L. Lynch, Reg. No. 30,871	Lia M. Pappas, Reg. No. 34,095	

as its attorneys with full power of substitution to prosecute this application and all applications claiming filing date priority therefrom and to transact all business in the U.S. Patent and Trademark Office in connection therewith.

The above-identified assignee hereby elects, pursuant to 37 C.F.R. § 3.71, to conduct the prosecution of the above-identified patent application to the exclusion of the inventor(s).

A chain of title from the inventor(s) of the above-identified patent application to the above-identified assignee is shown:

☐ In an assignment recorded in the U.S. Patent and Trademark Office at Reel, Frame.

☒ In an assignment filed herewith for recordation, a true copy of which is attached hereto.

The undersigned has reviewed the above-identified assignment and, to the best of his knowledge and belief, title is in the above-identified assignee.

The undersigned further avers that he is empowered to make and sign the foregoing certification on behalf of the above-identified assignee, and to take the action set forth herein on its behalf.

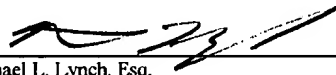
Please direct all communications regarding the above-identified application to:

Joseph A. Walkowski,  
 TRASK, BRITT & ROSSA  
 P.O. Box 2550  
 Salt Lake City, UT 84110  
 Tele: (801) 532-1922  
 Fax: (801) 531-9168

Respectfully Submitted,

MICRON TECHNOLOGY, INC.

Date: Jan 12, 2000

By:   
 Michael L. Lynch, Esq.  
 Reg. No. 30,871  
 Chief Patent Counsel,  
 MICRON TECHNOLOGY, INC.